

Centerline Technologies utilizes its expertise in making filled via's co-planar with the surface of the substrate. Depending on the height of the via protruding from the surface, Centerline Technologies will use a one or two step process in reducing the via height. It is strongly recommended to establish the process considerations with Centerline Technologies before building the circuits, so we can provide you with a better finished product.

Centerline Technologies will use its expertise in both lapping and polishing to maintain a flat and parallel surface on your finished substrates.

Considerations before filling Via's

- Thickness required of finished pieces
- Space between Via's
- Surface finish on material
- Via height after fill

It is very important to specify the starting thickness and flatness and parallelism of the substrate prior to filling via holes. The surface finish will be dependent on what your required surface finish is on the finished product.

Please be aware that materials machine at different rates and therefore, it is strongly recommended that you contact your vendor of choice before purchasing substrates to be filled. This will help provide the most economical and highest quality end product.

Centerline Technologies takes great pride in producing a superior product consistently and repeatedly. Please review our capabilities and polishing and lapping information. Talk to us. Ask questions. Find out why Centerline Technologies should be your preferred source for high quality polished and lapped substrate materials.

Centerline Technologies

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